

Leahkinn Technology Limited
Roadmap Q3 2020



Your Design & Business Partner in Mobile & Computing Industry





LPDDR
eMMC
eMCP
MCP and Others



LPDDR

LPDDR2 168/178B



Density	Technology	Q3	Q4	Q1 21	Q2 21	Q3 21
4Gb	38nm LP2 x1	 				
8Gb	38nm LP2 x2	 				

 Build To Order

 End of Life

LPDDR

LPDDR3 178B







Density	Technology	Q3	Q4	Q1 21	Q2 21	Q3 21
4Gb	25nm LP3 x1	● BTO				
8Gb	20nm LP3 x1	●				
16Gb	20nm LP3 x2	●				
24Gb	20nm LP3 x3	● BTO				
32Gb	20nm LP3 x4	● BTO				

LPDDR

LPDDR3 256B

PoP



Density	Technology	Q3	Q4	Q1 21	Q2 21	Q3 21
16Gb	20nm LP3 x2		 BTO			
32Gb	20nm LP3 x4	 BTO				

LPDDR

LPDDR4 200B



Density	Technology	Q3	Q4	Q1 21	Q2 21	Q3 21
4Gb	20nm LP4 x1	●	BTO			
8Gb	20nm LP4 x1	●		EoL		
16Gb	20nm LP4 x2	●		EoL		
16Gb	18nm LP4 x2	●				
24Gb	20nm LP4 x3	●		EoL		
24Gb	17nm LP4 x2	●				
32Gb	20nm LP4 x4	●	EoL			
32Gb	18nm LP4 x4	●	BTO			

eMMC

eMMC V5.1 153B





Density	Technology	Q3	Q4	Q1 21	Q2 21	Q3 21
8GB	2D MLC x1	●				
16GB	3D TLC x1	●				
32GB	3D TLC x1	●				
64GB	3D TLC x2	● BTO				

eMCP

LP2 eMCP V5.1 162B



Density	Technology	Q3	Q4	Q1 21	Q2 21	Q 21
8GB + 4Gb	2D MLC x1 + 38nm LP2 x1	 BTO				
8GB + 8Gb	2D MLC x1 + 38nm LP2 x2	 BTO				

eMCP

LP3 eMCP V5.1 221B



Density	Technology	Q3	Q4	Q1	Q2 21	Q3 21
8GB + 8Gb	2D MLC x1 + 20nm LP3 x1	●				
16GB + 8Gb	3D TLC x1 + 20nm LP3 x1	●				
16GB + 16Gb	2D MLC x2 + 20nm LP3 x2	●	EoL			
16GB + 16Gb	3D TLC x1 + 20nm LP3 x2	●				
32GB + 24Gb	2D MLC x4 + 25nm LP3 x4	●		EoL		

eMCP

LP4 eMCP V5.1 254B



Density	Technology	Q3	Q4	Q1 21	Q2 21	Q3 21
16GB + 16Gb	3D TLC x1 + 18nm LP4 x2	●				
32GB + 16Gb	3D TLC x1 + 18nm LP4 x2	●				
32GB + 24Gb	3D TLC x1 + 17nm LP4 x2	●				

NAND MCP

LP2 MCP 162B





Density	Technology	Q3	Q4	Q1	Q2 21	Q3 21
2Gb + 2Gb	24nm SLC x1 + 38nm LP2 x1	●				
4Gb + 2Gb	24nm SLC x1 + 38nm LP2 x1	●				
4Gb + 4Gb	24nm SLC x1 + 38nm LP2 x1	●				

PCDDR3/3-L

PCDDR3



Density	Technology	Q3	Q4	Q1 21	Q2 21	Q3 21
4Gb 96B	25nm 256 x16					
4Gb 78B	25nm 512 x 8					

Others

A. Leahkinn can customize different parameters to fit customers' requirement

- **Ball Out (134B, 168B, 253B, 256B, 272B, 366B and etc.)**
- **NAND / DRAM combination**
- **Speed / Power Budget**
- **Specific Test Flow**

B. Leahkinn also offered ODM business model for customized memory products

- **Hybrid Design (Different Die Size)**
- **ASIC + Memory SiP experience**